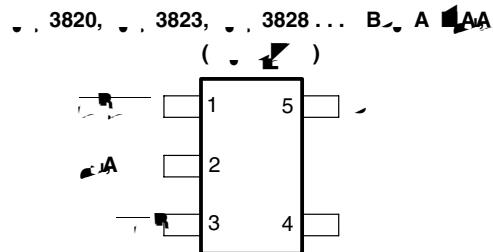


TPS3820-xx-Q1, TPS3823-xx-Q1, TPS3824-xx-Q1, TPS3825-xx-Q1, TPS3828-xx-Q1 PROCESSOR SUPERVISORY CIRCUITS

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- A 2000
- -883, 3015; B (= 100, 1500 Ω)
- 200 (. , 3823/4/5/8)
25 (. , 3820)
- (. , 3820/3/5/8)
- (. , 3820/3/4/5), A (. , 3824)
(. , 3828)
- 2.5, 3, 3.3, 5
- (. , 3820/3/4/8)
- 15 μ A (–)
- 23-5



- A A
- A A
- A
- A
- B
- A
- A

The TPS382x family of supervisors provides circuit initialization and timing supervision, primarily for DSP and processor-based systems.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date.
Products conform to specifications per the terms of Texas Instruments
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 **TEXAS
INSTRUMENTS**

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**TPS3820-xx-Q1, TPS3823-xx-Q1, TPS3824-xx-Q1, TPS3825-xx-Q1, TPS3828-xx-Q1
PROCESSOR SUPERVISORY CIRCUITS**

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X

C

TP
PR
x-Q1, TPS3824
RY CIRCUITS

SGI

NE 2008

**TPS3820-xx-Q1, TPS3823-xx-Q1, TPS3824-xx-Q1, TPS3825-xx-Q1, TPS3828-xx-Q1
PROCESSOR SUPERVISORY CIRCUITS**

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Supply voltage, V_{DD} (see Note 1)	6 V
RESET, \overline{RESET} , \overline{MR} , WDI (see Note 1)	-0.3 V to ($V_{DD} + 0.3$ V)
Maximum low output current, I_{OL}	5 mA
Maximum high output current, I_{OH}	-5 mA
Input clamp current range, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	± 10 mA
Output clamp current range, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	± 10 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	-40°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C
Soldering temperature	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

	A ≤ 25°	AB	A = 25°	A = 70°	A = 85°	A = 125°
DBV	437 mW	3.5 mW/°C		280 mW	227 mW	87 mW

	A	
Supply voltage, V_{DD}	1.1	5.5
Input voltage, V_I	0	$V_{DD} + 0.3$
High-level input voltage at \overline{MR} and WDI, V_{IH}	$0.7 \times V_{DD}$	V
Low-level input voltage, V_{IL}		$0.3 \times V_{DD}$
Input transition rise and fall rate at \overline{MR} or WDI, $\Delta t/\Delta V$	100	ns/V
Operating free-air temperature range, T_A	-40	125
		°C



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TPS
PRO

SGLS1

**TPS3820-xx-Q1, TPS3823-xx-Q1, TPS3824-xx-Q1, TPS3825-xx-Q1, TPS3828-xx-Q1
PROCESSOR SUPERVISORY CIRCUITS**

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A		Z	A	
$I_{IH(AV)}$	Average high-level input current	WDI	WDI = V_{DD} , time average (dc = 88%)	120
$I_{IL(AV)}$	Average low-level input current	WDI	WDI = 0.3 V, $V_{DD} = 5.5$ V time average (dc = 12%)	-15
I_{IH}	High-level input current	WDI	WDI = V_{DD}	140 190
		MR	MR = $V_{DD} \times 0.7$, $V_{DD} = 5.5$ V	-40 -60
I_{IL}	Low-level input current	WDI	WDI = 0.3 V, $V_{DD} = 5.5$ V	140 190
		MR	MR = 0.3 V, $V_{DD} = 5.5$ V	-110 -160
I_{OS}	Output short-circuit current (see Note 4)	TPS382x-25	$V_{DD} = V_{IT, \text{max}} + 0.2$ V, $V_O = 0$ V	-400
		TPS382x-30		-800
		TPS382x-33		
		TPS382x-50		
I_{DD}	Supply current	WDI and MR unconnected, Outputs unconnected	15 25	μA
Internal pullup resistor at MR			52	$\text{k}\Omega$
C_i	Input capacitance at MR, WDI	$V_I = 0$ V to 5.5 V	5	pF

NOTE 4: The RESET short-circuit current is the maximum pullup current when RESET is driven low by a μP bidirectional reset pin.

A		Z	A	
t_w	at V_{DD}	$V_{DD} = V_{IT-} + 0.2$ V, $V_{DD} = V_{IT-} - 0.2$ V	6	μs
	at MR	$V_{DD} \geq V_{IT-} + 0.2$ V, $V_{IL} = 0.3 \times V_{DD}$, $V_{IH} = 0.7 \times V_{DD}$	1	μs
	at WDI	$V_{DD} \geq V_{IT-} + 0.2$ V, $V_{IL} = 0.3 \times V_{DD}$, $V_{IH} = 0.7 \times V_{DD}$	100	ns

A		Z	A	
t_{out}	Watchdog time out	TPS3820	$V_{DD} \geq V_{IT-} + 0.2$ V, See Timing Diagram	112 200 310 ms
		TPS3823/4/8		0.9 1.6 2.5 s
t_d	Delay time	TPS3820	$V_{DD} \geq V_{IT-} + 0.2$ V, See timing diagram	15 25 37 ms
		TPS3823/4/5/8		120 200 300

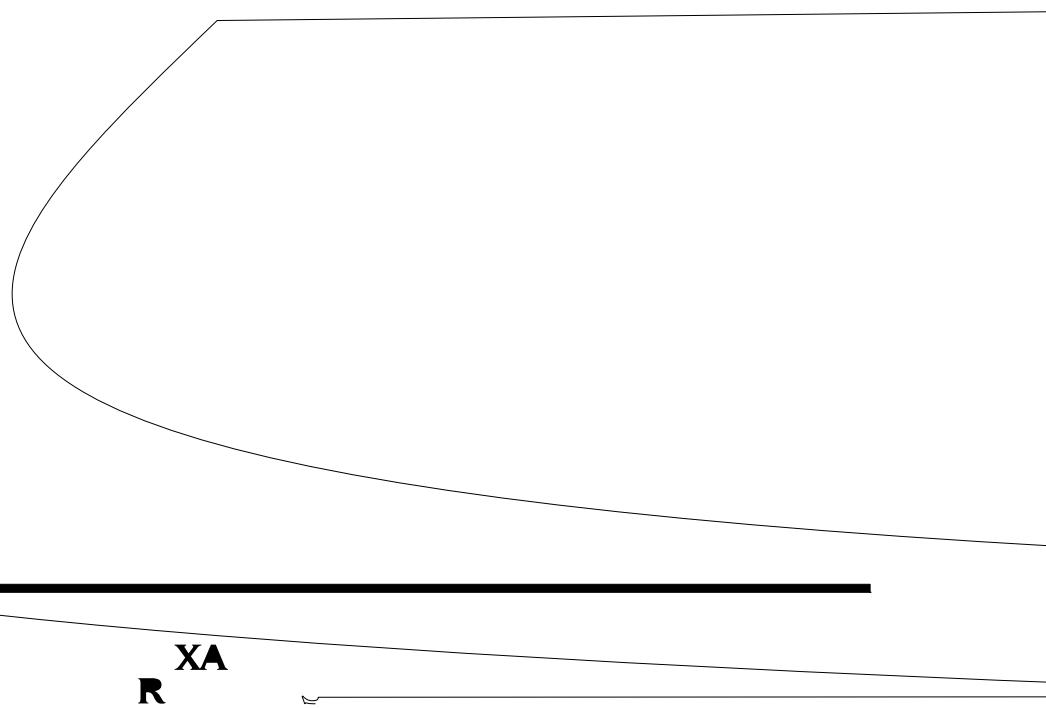
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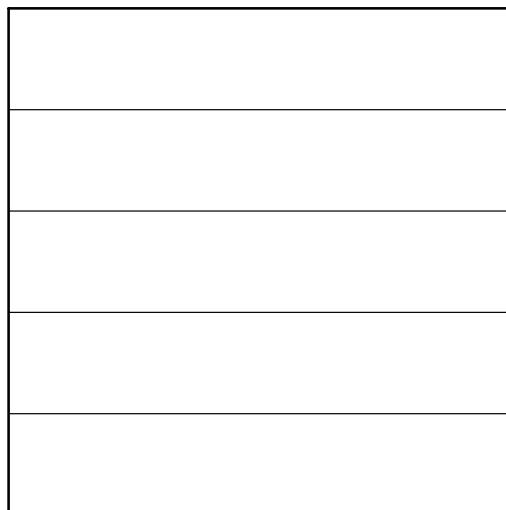
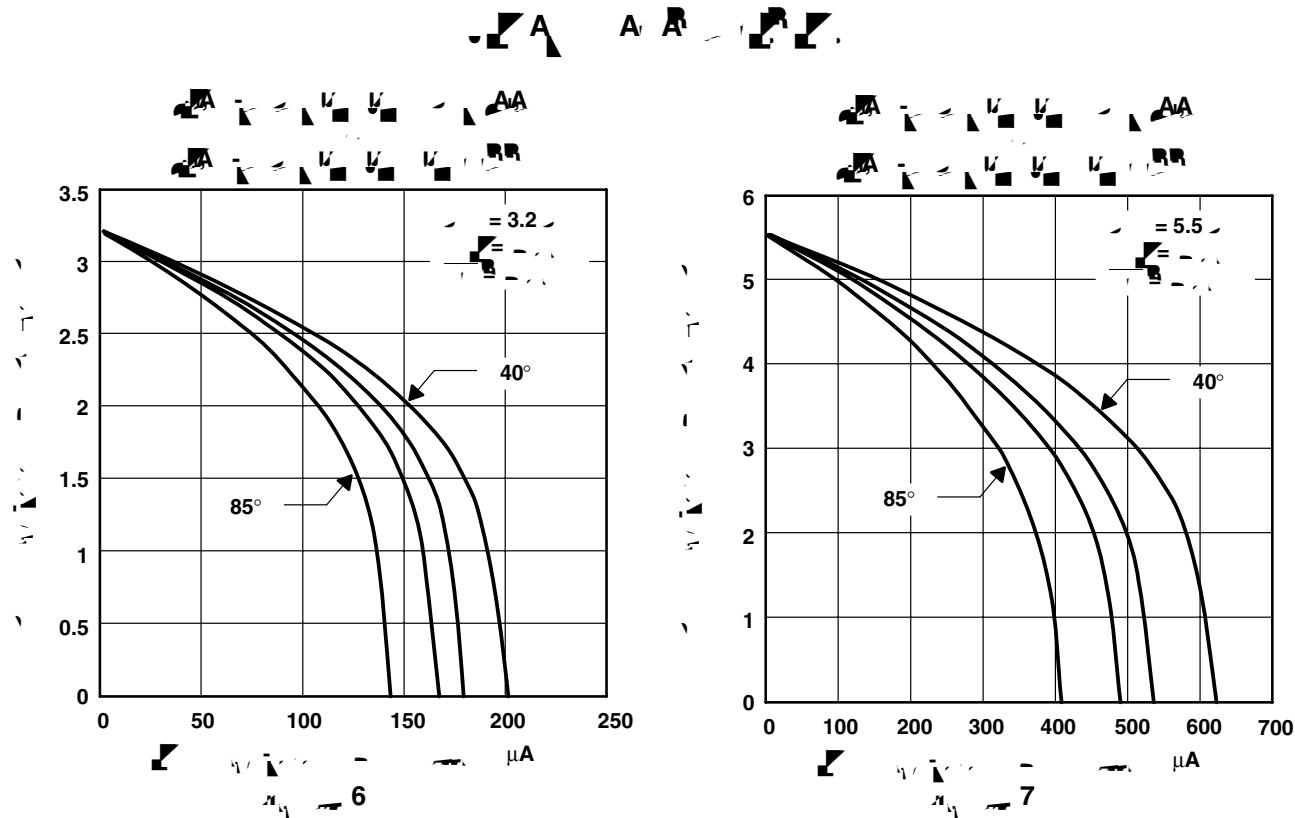
**TPS3820-xx-Q1, TPS3823-xx-Q1, TPS3824-xx-Q1, TPS3825-xx-Q1, TPS3828-xx-Q1
PROCESSOR SUPERVISORY CIRCUITS**

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**TPS3820-xx-Q1, TPS3823-xx-Q1, TPS3824-xx-Q1, TPS3825-xx-Q1, TPS3828-xx-Q1
PROCESSOR SUPERVISORY CIRCUITS**

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
2T25-50QFRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDFQ	Samples
2T28-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDIQ	Samples
2U3820-50QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDDQ	Samples
2U3823-25QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAPQ	Samples
2U3823-30QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAQQ	Samples
2U3823-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PARQ	Samples
2U3823-50QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PASQ	Samples
2U3824-25QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PATQ	Samples
2U3824-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAVQ	Samples
2U3824-50QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAWQ	Samples
2U3825-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDGQ	Samples
TPS3820-33QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDEQ	Samples
TPS3820-50DBVRQ1G4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PKG4	Samples
TPS3820-50QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDDQ	Samples
TPS3823-25QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAPQ	Samples
TPS3823-30QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAQQ	Samples
TPS3823-33QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PARQ	Samples



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PACKAGE OPTION ADDENDUM

24-Jan-2013

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)
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(4) Only one of markings shown within the brackets will appear on the physical device.

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- Catalog: [TPS3820-33](#), [TPS3820-50](#), [TPS3823-25](#), [TPS3823-30](#), [TPS3823-33](#), [TPS3823-50](#), [TPS3824-25](#), [TPS3824-30](#), [TPS3824-33](#), [TPS3824-50](#), [TPS3825-33](#), [TPS3825-50](#), [TPS3828-33](#), ,

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
2T25-50QFRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2T28-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3820-50QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-25QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-30QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-50QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3824-25QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3824-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3824-50QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3825-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3820-33QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3820-50DBVRQ1G4	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3820-50QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-25QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-30QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-33QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-50QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3

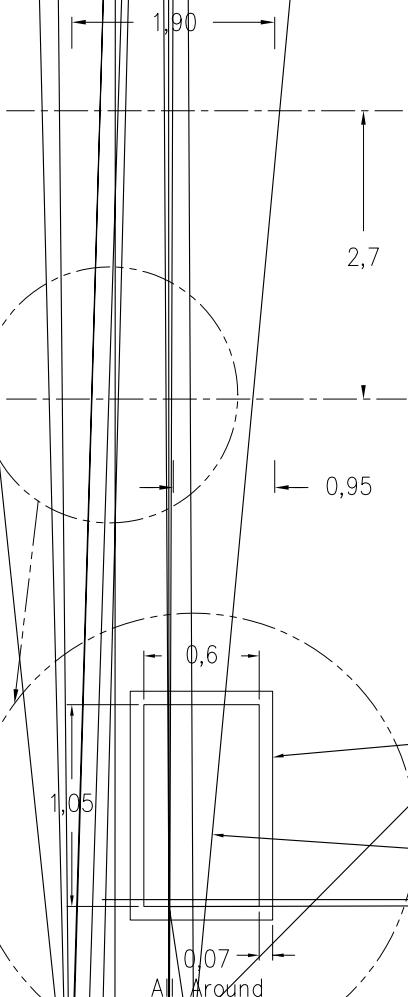
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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
2U3824-50QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3825-33QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3820-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3820-50DBVRQ1G4	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3820-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-25QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-30QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3824-30QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3824-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3824-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3825-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3825-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3828-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3828-50QDBVRG4Q	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3828-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0

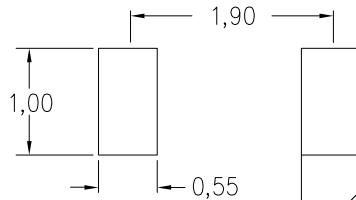
LAND PATTERN DATA

PLASTIC SMALL OUTLINE

Example Board Layout



Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is for information only.

D. Publication IPC-7351 is recommended for alternate designs.

E. Solder mask openings should have a 50% overlap. Tidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% overlap.

4209593-3/C 08/11

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